Capital management

Haviv Ilan, president, chief executive officer Rafael Lizardi, senior vice president, chief financial officer Dave Pahl, vice president, head of investor relations

August 20, 2024, 10 a.m. Central time

Off-cycle capital management update; agenda

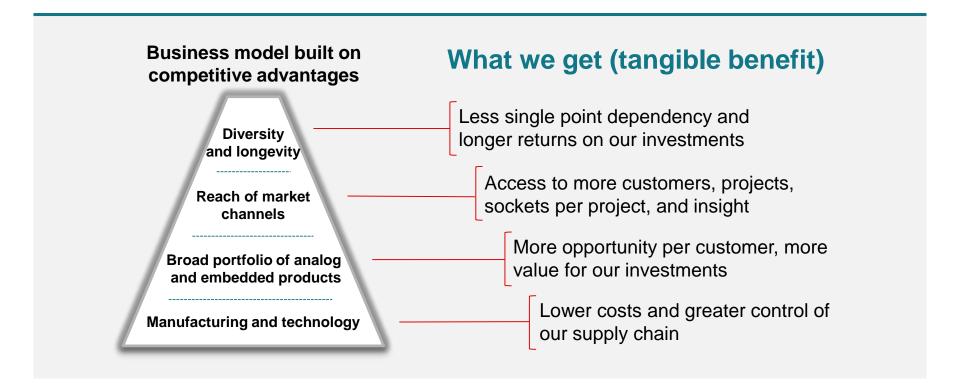
We are more than 60% through a six-year elevated CapEx cycle that, when completed, will uniquely position TI for the next 10 to 15 years to deliver:

- Dependable, low-cost 300mm capacity to meet customers' demand
- Scalability of CapEx, including capacity modularity
- Free cash flow per share growth across a range of market conditions

Today we will provide:

- Insight into our growth expectations
- Granularity on our capacity investments in 300mm wafer fabs
- A framework of revenue scenarios across various market conditions, and associated ranges of CapEx and free cash flow per share

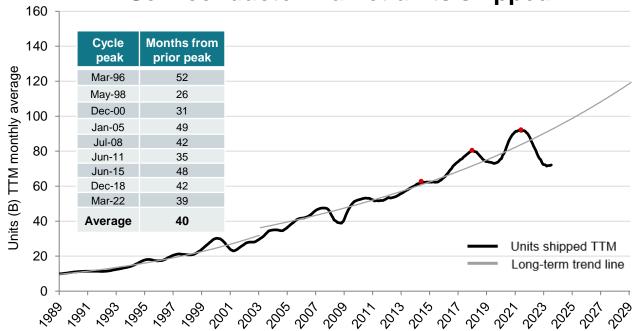
Building competitive advantages unique to TI



Insight into our growth expectations

Semiconductor cycles: planning for the long term

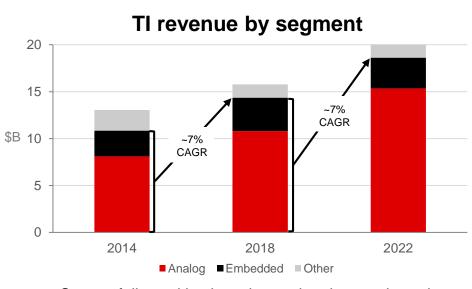




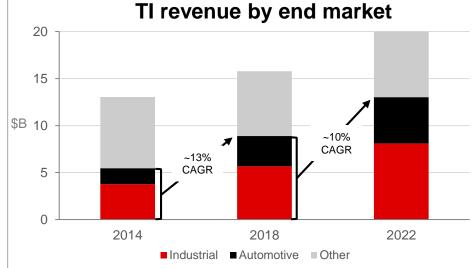
- Market environment remains weak, with shipments below 2019 levels.
- Last three peaks inform our preparation for the opportunity ahead.
- We are prepared for a range of market recovery scenarios.

^{*} Source: WSTS excluding memory trailing twelve months through June 2024

Portfolio and market positions have strengthened



- Our portfolio position has changed and strengthened
- "Other" segment is now small and stable
- Expect Analog and Embedded to drive future growth



- Our exposure to industrial and automotive has increased
- These markets likely continue to be the fastest growing
- We are well-positioned for future growth

Advancing technologies in industrial, automotive

TI product portfolio addresses an increasing number of sockets across all sectors

Factory automation, motor drives & robotics

2023: ~\$2B growing ~10%*





Collaborative robot (cobot)

\$400+ content, 200+ chips per cobot

Application specific: vision processor, radar, C2000 real-time control. GaN

General purpose: MCU, power management, analog signal chain

Energy infrastructure

2023: ~\$1B growing ~10%*



Solar (panel, inverter, storage)

\$350+ content, 200+ chips per system

Application specific: BMS, C2000 real-time control, GaN, wireless connectivity, data converters

General purpose: power management, analog signal chain

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Industrial

Body electronics & lighting

2023: \$1B+ growing ~20%*



Vehicle body & lighting system

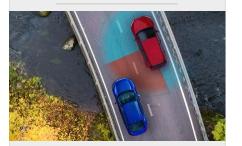
\$250+ content, 500+ chips per vehicle

Application specific: matrix headlight, wireless connectivity, motor driver, radar

General purpose: MCU, power management, analog signal chain

Advanced driver assistance systems

2023: ~\$1.5B growing ~20%*



Vehicle ADAS system

\$350+ content, 300+ chips per system

Application specific: radar, FPD-Link, safety power, vision processor

General purpose: power management, analog signal chain

Automotive

*10-year CAGR from 2013 through 2023



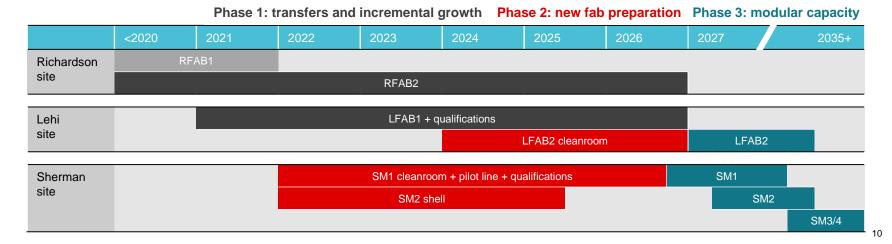
In summary: TI is positioned to grow

- Market exposure: Industrial and automotive have grown from about 40% in 2014 to about 75% of TI's revenue in 2023, with double-digit growth through the last two peaks.
- **Stronger portfolio:** Breadth of analog and embedded products, combined with investments in process and package technologies, strengthens product portfolio.
- **Positioned to grow:** Our exposure to large, fast growing markets <u>and</u> our strong portfolio of analog and embedded position us to capture the opportunity ahead.

Capacity investments in 300mm wafer fabs

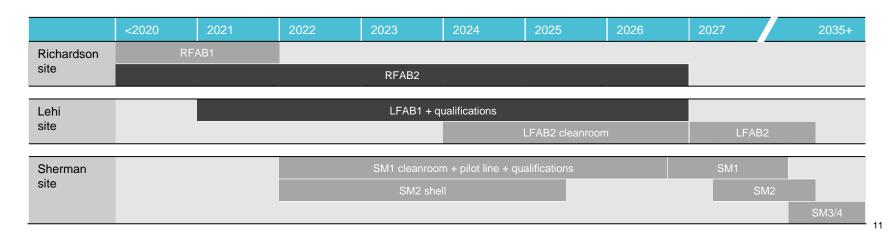
Position TI to deliver:

- 1. Dependable, low-cost 300mm capacity to meet customers' demand, given increasing semiconductor content in industrial and automotive, especially in a world with rising geopolitical tensions
- 2. Scalability of CapEx, including capacity modularity, to handle strong markets or times of persistent market weakness
- 3. Free cash flow per share growth across a range of market conditions



Phase 1 (2021-2026) Transfers & incremental growth

- Equip RFAB2 and execute 150mm fab shutdowns, transfer into RFAB2
- Equip LFAB1 and complete technology and customer qualification
- · Transfer external foundry wafers into LFAB1

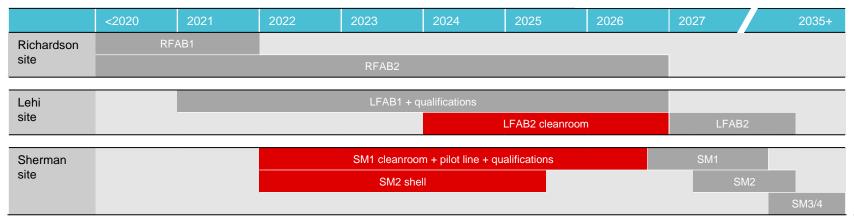


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Phase 2 (2022-2026) New fab preparation

- LFAB2 cleanroom ready for first production start, no customer re-qualification needed
- Construct SM1 and complete pilot line to begin technology and customer qualification
- Complete SM2 shell, eliminating construction lead time



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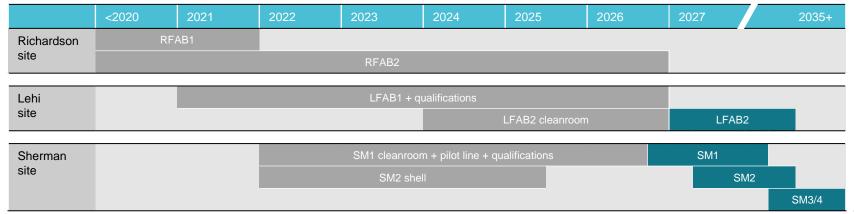
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Phase 3 (2026+) Modular capacity

- Ramp fabs to meet customers' demand, without re-qualifications
- Scalability of CapEx, including capacity modularity
- Deliver free cash flow per share growth across a range of market conditions



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Our 300mm wafer fab manufacturing footprint

Execution progressing well across all three sites

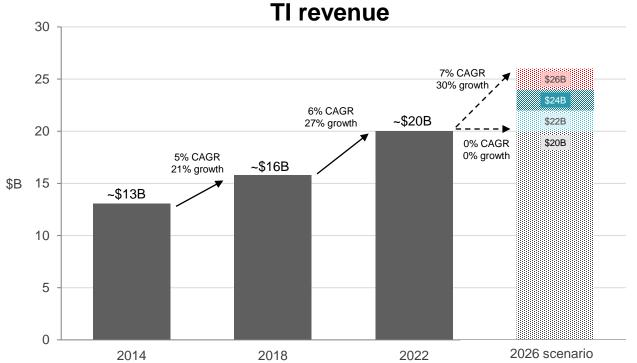
| | RFAB2 | LFAB1 | LFAB2 | SM1 | SM2 | SM3/4 |
|-------------------------------------|----------------------------------|------------------------------------|------------------|------------------|----------------|----------------|
| | RFAB2 RFAB1 | LFAB1 | LFAB2 | | SM4 SM1 | SM2 |
| Groundbreaking | 2020 | Acquired 2021 | 2023 | 2022 | 2022 (shell) | TBD |
| Production (initial/fully equipped) | 2022/2026 | 2022/2026 | 2026/TBD | 2025/TBD | TBD | TBD |
| Maximum revenue supported* | ~\$6B | ~\$4B | ~\$11B | ~\$9B | TBD | TBD |
| СарЕх | ~\$6B | ~\$4B | ~\$11B | ~\$30-40B | | |
| Process technology | 130-180nm | 28-65nm | 28-65nm | 65-130nm | 65-130nm | 28-130nm |
| Source of demand | Organic growth & 150mm transfers | Insourcing from external foundries | Organic growth | Organic growth | Organic growth | Organic growth |
| CHIPS ITC eligibility | 25% through 2026 | 25% through 2026 | 25% through 2034 | 25% through 2032 | | |

* Dependent on mix and utilization

Delivering free cash flow per share growth across a range of market conditions

Four revenue scenarios

Range of market conditions modeled toward 2026



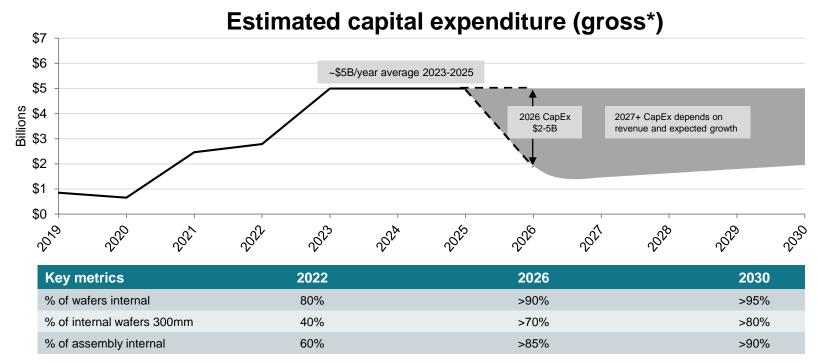
| 2026 revenue | CAGR (vs 2022) | Absolute growth (vs 2022) |
|-----------------|-------------------|------------------------------|
| \$26B | 7% | 30% |
| \$24B | 5% | 20% |
| \$22B | 2% | 10% |
| \$20B* | 0% | 0% |

- We chose 2026 for scenario planning to show a range of market conditions.
- The higher revenue scenario indicates a rapid market recovery from today.
- The zero growth scenario would indicate a persistently weak market, which likely means the next industry peak is delayed.

^{*} Latest analyst consensus from Capital IQ

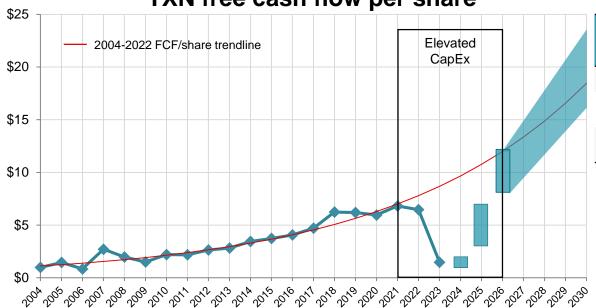
Scalability of capital expenditures

Supports long-term growth



Revenue scenarios deliver free cash flow per share growth

TXN free cash flow per share



| | 2026 revenue scenario | \$20B | \$22B | \$24B | \$26B |
|--|--------------------------|--------|--------|---------|---------|
| | CAGR | 0% | 2% | 5% | 7% |
| | CapEx | \$2-3B | \$2-3B | \$3-4B | \$4-5B |
| | FCF/Share | \$8-9 | \$9-10 | \$10-11 | \$11-12 |

- Free cash flow per share will begin to approach trendline in 2026 as growth returns and CapEx begins to moderate.
- We are prepared to support a rapid market recovery or a persistently weak market.
- Long-term free cash flow per share growth guides our capital allocation decisions.

Free cash flow per share trend line continues at ~11%. CapEx flat at \$5 billion through 2025, then aligned to revenue scenario. CHIPS ITC included; no proposed direct funding assumed.

Summary

We are more than 60% through a six-year elevated CapEx cycle that, when completed, will **uniquely position TI for the next 10 to 15 years to deliver:**

- 1. Dependable, low-cost 300mm capacity to meet customers' demand
- 2. Scalability of CapEx, including capacity modularity
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Risk factors and non-GAAP measures

This presentation is a statement of management's intentions and describes a strategy that TI intends to pursue as management, in its judgment, deems appropriate. The application of this strategy during any given period may vary depending on market conditions and other factors that management deems relevant. This presentation includes forward-looking statements intended to qualify for the safe harbor from liability established by the Private Securities Litigation Reform Act of 1995. See Item 1A of TI's most recent Form 10-K for a detailed discussion of risk factors that may cause results to differ materially from the forward-looking statements. TI undertakes no obligation to update forward-looking statements to reflect subsequent events or circumstances.

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